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## 4<sup>th</sup> Asia-Pacific Conference on Plasma Physics, 26-31Oct, 2020, Remote e-conference **Fast pulsed non-thermal plasmas for catalyst-free and catalytic CH<sub>4</sub> activation**

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The CH<sub>4</sub> pyrolysis needs very high temperature due to the strong C-H bands of 435 kJ/mol. Non-oxidative CH<sub>4</sub> conversion to value-added chemicals generally requires specific catalytic condition, whereas electricity-driven technology is supposed to be highly promising to realize these processes with basic ambient.<sup>1,2</sup> In this paper, CH<sub>4</sub> activation by high-energy electron collision, fast gas heating process, or energy pooling of Ar metastable particles were verified and regulated in fast pulsed non-thermal plasmas (dielectric barrier discharge (DBD), spark discharge, CH<sub>4</sub>/Ar discharge, respectively).<sup>3-5</sup>

In DBD plasma, abundant of CH<sub>3</sub> radicals formed by electron-induced reaction (e+CH<sub>4</sub>  $\rightarrow$  CH<sub>3</sub>+H+e) could couple to C<sub>2</sub>H<sub>6</sub> at low temperature (even near room temperature, shown as Fig. 1), while would also enhance the free radical chain reaction (CH<sub>3</sub>+CH<sub>4</sub> $\rightarrow$ C<sub>2</sub>H<sub>6</sub>+H) in plasma-catalytic CH<sub>4</sub> activation at high temperature (1253 K). The effects of pulse parameters (polarity, frequency, rising/falling time and width) on CH<sub>4</sub> conversion and C<sub>2</sub>H<sub>6</sub> yield were understood and optimized by combined utilizations of experiment, diagnosis and simulation.

In spark discharge plasma, CH<sub>4</sub> gas molecules could be heated to ~2000 K within dozens of nanoseconds, bringing out very high CH<sub>4</sub> conversion,  $C_2H_2/H_2$  yield and energy utilization efficiency, and then  $C_2H_2$  will be adequately hydrogenated to  $C_2H_4$  when adding 0.5%Pd/CeO<sub>2</sub> catalyst after plasma area. Within single pulse, vibrational temperature drops dramatically from over 6000 K to 2000 K (shown as Fig. 2), which indicates that the vibrational-rotational energy relaxation may play an important role in the electrical-thermal energy transfer process.

In CH<sub>4</sub>/Ar discharge plasma, except for the direct electron impact dissociation during the pulse-on period, both the charge transfer between  $Ar^+$  and  $CH_4$  and the quenching of Ar metastable species by CH<sub>4</sub> contribute to a further increase of CH<sub>4</sub> dissociation degree during the pulse-off period (i.e. the  $Ar^+$  and Ar metastable species can function as an energy pooling for the formation of H and hydrocarbon radicals). Specially, the evolution of the absolute density of the hydrogen atom at the ground state, as a real-time and *in-situ* indicator of the CH<sub>4</sub> dissociation degree, is measured using the two-photon absorption laser induced fluorescence (TALIF) method (shown as Fig. 3). The innovative approaches proposed in this work may contribute to the catalyst-free and catalytic CH<sub>4</sub> activation by non-thermal plasmas.

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Fig. 1. Typical OES and simulation of gas temperatures in the two form microsecond pulsed CH<sub>4</sub> DBD plasmas.<sup>3</sup>



Fig. 2. Time evolution of (a): current and typical OES and (b): vibrational and rotational temperatures in the pulsed spark discharge plasma.<sup>4</sup>



Fig. 3. Dots: the measured temporal evolution of the H atom density using the TALIF. Curves: the calculated temporal evolution of the H atom density using the reaction kinetic model.<sup>5</sup>

References

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